

IN THE SPECIFICATION

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Please amend the paragraph beginning at page 17, line 20, through page 17, line 26, as follows:

The entire structure of a PEB device 1 is a single system that is controlled by a controller 22. Four temperature sensors 26, 27, 28, and 29 and one built-in thermometer (not shown) are connected to input sections of the controller 22, and thus each of the sensors inputs a detected temperature signal to the unit. The first temperature sensor 26 is mounted on a hot plate 2, and thus a temperature TP of the hot plate 2 is detected. For the first temperature sensor 26, a contact-type thermocouple or a platinum resistance thermometer, for example, is used. The second temperature sensor is provided above a wafer W placed on the hot plate 2, and thus an upper surface temperature TS of the wafer W is detected. For the second temperature sensor 27, a non-contact-type optical temperature sensor (heat sensitive sensor), for example, is used. The third temperature sensor 28 is provided in a heat space 30, and thus a temperature TH of the heat space is detected. For the third temperature sensor 28, a contact-type thermocouple or a platinum resistance thermometer or a non-contact-type optical temperature sensor (heat sensitive sensor) may be used. The fourth temperature sensor 29 is provided in a fluid space 31, and thus a temperature TF of the fluid space is detected. For the fourth temperature sensor 29, a contact-type thermocouple, a platinum resistance thermometer or a non-contact-type optical temperature sensor (heat sensitive sensor) may be used. The fifth built-in temperature meter (~~not shown~~) 7a is provided inside a filter adjustment mechanism 7, and thus the temperature of a filter 6 is detected. For the fifth built-in temperature sensor 28, a contact-type thermocouple or a platinum resistance thermometer, for example, is used.